Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"20030089988"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 15:46
L7	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L8	57	air with barrier with (silicon near2( nitride carbonitride oxynitride oxide dioxide carbide) fluronited near2 glass)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L9	8	air near2 barrier with ( silicon near2 (nitride carbonitride oxynitride dioxide carbide fluorinated near2 glass))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L10	43	air with barrier with ( silicon near2 (nitride carbonitride oxynitride dioxide carbide fluorinated near2 glass))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L11	43	air with barrier with (silicon near2( nitride carbonitride oxynitride dioxide carbide) fluronited near2 glass)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM TDB	OR	ON	2006/02/13 16:01
L12	14	L8 not L11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM TDB	OR	ON	2006/02/13 16:01
L13	2	"5895971".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L14	6	("5461197"   "5627407"   "5641996"   "5646204").PN. OR ("5895971"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/13 16:01
L15	1	"5814536".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/13 16:01

			110 00 5115	00	011	000000000
L16	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L17	1444	(257/751).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L18	3625	(257/758).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L19	846	(257/760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L20	955	(438/627).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L21	1445	(438/643).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L22	3027	(438/624).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L23	9773	L16 L17 L18 L19 L20 L21 L22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L24	2354	L23 and diffusion with barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01

L25	79	L24 and air with barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L26	55	L25	USPAT	OR	ON	2006/02/13 16:01
L27	39	air near2 permeation with barrier	USPAT	OR	ON	2006/02/13 16:01
L28	0	L27 and interconnect	USPAT	OR	ON	2006/02/13 16:01
L29	0	L27 and "257"/\$.ccls.	USPAT	OR	ON	2006/02/13 16:01
L30	173	air near2 permeation and barrier with barrier	USPAT	OR	ON	2006/02/13 16:01
L31	1	L30 and "257"/\$.ccls.	USPAT	OR	ON	2006/02/13 16:01
L32	0	L30 and "438"/\$.ccls.	USPAT	OR	ON	2006/02/13 16:01
L33	0	air near2 diffussion and barrier with barrier	USPAT	OR	ON	2006/02/13 16:01
L34	0	air near2 difussion and barrier with barrier	USPAT	OR	ON	2006/02/13 16:01
L35	529	air near2 diffusion and barrier	USPAT	OR	ON	2006/02/13 16:01
L36	15	L35 and "257"/\$.ccls.	USPAT	OR	ON	2006/02/13 16:01
L37	816	air near2 impermea\$5 and barrier with barrier	USPAT	OR	ON	2006/02/13 16:01
L38	816	air near2 impermea\$5 and barrier	USPAT	OR	ON	2006/02/13 16:01
L39	8	L38 and "257"/\$.ccls.	USPAT	OR	ON	2006/02/13 16:01
L40	158	air near2 impermea\$5 and interconnect	USPAT	OR	ON	2006/02/13 16:01
L41	304	interconnect and air near2 cap	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L42	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L43	1444	(257/751).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L44	3625	(257/758).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01

L45	846	(257/760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L46	955	(438/627).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L47	1445	(438/643).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L48	3027	(438/624). CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L49	9773	L42 L43 L44 L45 L46 L47 L48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L50	3	L41 and L49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L51	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L52	0	"Si.sub.\$3N.sub.\$3C.sub.\$3O.sub. \$H.sub.\$3"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L53	5	"Si.sub.vN.sub.wC.sub.xO.sub.yH. sub.z"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01

L54	0	"Si.sub.\$N.sub.\$C.sub\$O.sub.\$H. sub.z"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM TDB	OR	ON	2006/02/13 16:01
L55	0	"Si.sub.\$N.sub.\$C.sub\$O.sub.\$H. sub.z"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L56	0	"Si.sub.\$N.sub.\$C.sub\$O.sub.\$H. sub.z"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L57	0	SiNCOH	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L58	0	SiNCOH .	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L59	819	Si\$N\$C\$O\$H	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 20:18
L60	44	L59 and interconnect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L61	44	L59 and interconnect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L62	44	L61 not"single-instruction-multiple-datap ath "	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01

L63	24	L61 not "single-instruction-multiple-datapath "	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L64	4	L59 and 257/7\$2.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L65	18176	Si\$N\$C\$H	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L66	139	L65 and 257/7\$2.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L67	30	("20020024150"   "20020048929"   "20020048931"   "20020052125"   "20020117737"   "20020117754"   "20020117760"   "20020130416"   "20020130417"   "20020137323"   "20020164865"   "20020164889"   "20030001273"   "20030089988"   "20030183939"   "6159842"   "6187663"   "6245662"   "6265779"   "6265780"   "6358842"   "6362091"   "6380091"   "6383920"   "6391757"   "6395632"   "6406994"   "6472306"   "6486557"   "6573604").PN. OR ("6917108").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/13 16:01
L68	130	SiCOH with dielectric near2 constant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L69	8	air near2 barrier with ( silicon near2 (nitride carbonitride oxynitride dioxide carbide fluorinated near2 glass))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L70	43	air with barrier with ( silicon near2 (nitride carbonitride oxynitride dioxide carbide fluorinated near2 glass))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01

L71	1444	(257/751).CCLS.	US-PGPUB;	OR	OFF	2006/02/13 16:01
			USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB			
L72	3625	(257/758). CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L73	846	(257/760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L74	955	(438/627).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L75	1445	(438/643). CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L76	3027	(438/624).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L77	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L78	9773	L77 L71 L72 L73 L74 L75 L76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L79	2354	L78 and diffusion with barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L80	39	air near2 permeation with barrier	USPAT	OR	ON	2006/02/13 16:01
L81	0	L80 and interconnect	USPAT	OR	ON	2006/02/13 16:01

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L82	0	L80 and "257"/\$.ccls.	USPAT	OR	ON	2006/02/13 16:01
L83	173	air near2 permeation and barrier with barrier	USPAT	OR	ON	2006/02/13 16:01
L84	0	L83 and "438"/\$.ccls.	USPAT	OR	ON	2006/02/13 16:01
L85	0	air near2 diffussion and barrier with barrier	USPAT	OR	ON	2006/02/13 16:01
L86	0	air near2 difussion and barrier with barrier	USPAT	OR	ON	2006/02/13 16:01
L87	529	air near2 diffusion and barrier	USPAT	OR	ON	2006/02/13 16:01
L88	816	air near2 impermea\$5 and barrier with barrier	USPAT	OR	ON	2006/02/13 16:01
L89	816	air near2 impermea\$5 and barrier	USPAT	OR	ON	2006/02/13 16:01
L90	304	interconnect and air near2 cap	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L91	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L92	1444	(257/751).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L93	3625	(257/758).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L94	846	(257/760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L95	955	(438/627).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L96	1445	(438/643).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01

L97	3027	(438/624).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L98	9773	L91 L92 L93 L94 L95 L96 L97	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L99	0	"Si.sub.\$3N.sub.\$3C.sub.\$3O.sub. \$H.sub.\$3"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L100	0	"Si.sub.\$N.sub.\$C.sub\$O.sub.\$H. sub.z"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L101	0	"Si.sub.\$N.sub.\$C.sub\$O.sub.\$H. sub.z"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L102	0	"Si.sub.\$N.sub.\$C.sub\$O.sub.\$H. sub.z"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L103	0	SiNCOH	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L104	0	SiNCOH	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L105	819	Si\$N\$C\$O\$H	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01

L106	44	L105 and interconnect	US-PGPUB;	OR	ON	2006/02/13 16:01
			USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB			
L107	44	L106 not"single-instruction-multiple-datap ath "	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L108	18176	Si\$N\$C\$H	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L109	1	"5814536".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/13 16:01
L110	1	L83 and "257"/\$.ccls.	USPAT	OR	ON	2006/02/13 16:01
L111	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/02/13 16:01
L112	57	air with barrier with (silicon near2( nitride carbonitride oxynitride oxide dioxide carbide) fluronited near2 glass)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L113	43	air with barrier with (silicon near2( nitride carbonitride oxynitride dioxide carbide) fluronited near2 glass)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L114	. 14	L112 not L113	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L115	2	"5895971".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L116	6	("5461197"   "5627407"   "5641996"   "5646204").PN. OR ("5895971"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/13 16:01

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L117	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L118	79	L79 and air with barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L119	55	L118	USPAT	OR	ON	2006/02/13 16:01
L120	15	L87 and "257"/\$.ccls.	USPAT	OR	ON	2006/02/13 16:01
L121	8	L89 and "257"/\$.ccls.	USPAT	OR	ON	2006/02/13 16:01
L122	3	L90 and L98	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L123	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L124	5	"Si.sub.vN.sub.wC.sub.xO.sub.yH. sub.z"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L125	44	L105 and interconnect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L126	44	L105 and interconnect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L127	24	L106 not "single-instruction-multiple-datapath"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01

L128	4	L105 and 257/7\$2.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM TDB	OR	ON	2006/02/13 16:01
L129	30	("20020024150"   "20020048929"   "20020048931"   "20020052125"   "20020117737"   "20020117754"   "20020117760"   "20020130416"   "20020130417"   "20020137323"   "20020164865"   "20020164889"   "20030001273"   "20030089988"   "20030183939"   "6159842"   "6187663"   "6245662"   "6265779"   "6265780"   "6358842"   "6362091"   "6380091"   "6383920"   "6391757"   "6395632"   "6406994"   "6472306"   "6486557"   "6573604").PN. OR ("6917108").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/13 16:01
L130	158	air near2 impermea\$5 and interconnect	USPAT	OR	ON	2006/02/13 16:01
L131	139	L108 and 257/7\$2.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L132	130	SiCOH with dielectric near2 constant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L133	o	("5034241.pn.").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/13 16:01
L134	2	"5034241".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L135	7	("2632705"   "4861614").PN. OR ("5034241").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/13 16:01
L136	44	interconnect same air near2 barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L137	3	("2002/0164889").URPN.	USPAT	OR	ON	2006/02/13 16:01

L138	30	("20020024150"   "20020048929"   "20020048931"   "20020052125"   "20020117737"   "20020117754"   "20020117760"   "20020130416"   "20020130417"   "20020137323"   "20020164865"   "20020164889"   "20030001273"   "20030089988"   "20030183939"   "6159842"   "6187663"   "6245662"   "6265779"   "6265780"   "6358842"   "6362091"   "6380091"   "6383920"   "6391757"   "6395632"   "6406994"   "6472306"   "6486557"   "6573604").PN. OR ("6917108").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/13 16:01
L139	2	"20020130417".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L140	2	"20030089988".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L141	2	"6,265,779".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L142	2	wo-9826452-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L143	2	"20020093088".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L144	2	jp-03185742-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01
L145	2	"6249053".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 16:01

L146	4	("6265779"\"6917108").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/13 17:59	
L147	1900	(interconnect\$3 and Si\$N\$C\$O\$H adn barrier and air).clm.	US-PGPUB	OR	ON	2006/02/13 20:19	
L148	o	(interconnect\$3 and Si\$N\$C\$O\$H and barrier and air).clm.	US-PGPUB	OR	ON	2006/02/13 20:20	
L149	0	(interconnect\$3 and Si\$N\$C\$O\$H and barrier).clm.	US-PGPUB	OR	ON	2006/02/13 20:19	
L150	1	(interconnect\$3 and Si\$N\$C\$O\$H ). clm.	US-PGPUB	OR	ON	2006/02/13 20:19	
L151	0	((IC integrated near1 circuit chip die wafer silicon semiconductor) and Si\$N\$C\$O\$H and barrier and air). clm.	US-PGPUB	OR	ON	2006/02/13 20:21	
L152	0	((IC integrated near1 circuit chip die wafer silicon semiconductor) and Si\$N\$C\$O\$H and barrier).clm.	US-PGPUB	OR	ON	2006/02/13 20:21	
L153	0	((IC integrated near1 circuit chip die wafer silicon semiconductor) and Si\$N\$C\$O\$H and air).clm.	US-PGPUB	OR	ON	2006/02/13 20:21	
L154	1	((IC integrated near1 circuit chip die wafer silicon semiconductor) and Si\$N\$C\$O\$H).clm.	US-PGPUB	OR	ON	2006/02/13 20:21	
L155	2	( (film layer coat\$3) and Si\$N\$C\$O\$H ).clm.	US-PGPUB	OR	ON	2006/02/13 20:30	
L156	1	"6265779".pn.	USPAT	OR	ON	2006/02/13 20:44	
L157	1	"20020130417".pn.	US-PGPUB; USPAT	OR	ON	2006/02/13 20:44	
L158	1	"20030089988".pnpn.	US-PGPUB; USPAT	OR	ON	2006/02/13 20:45	